## **SELF-OSCILLATING HALF-BRIDGE**

#### **Features**

- Output Power MOSFETs in half-bridge configuration 400V Rated Breakdown Voltage
- High side gate drive designed for bootstrap operation
- Bootstrap diode integrated into package
- Accurate timing control for both Power MOSFETs Matched delay to get 50% duty cycle Matched deadtime of 1.2us
- Internal oscillator with programmable frequency

$$f = \frac{1}{1.4 \times (RT + 75\Omega) \times CT}$$

- Zener clamped Vcc for offline operation
- Half-bridge output is out of phase with R<sub>T</sub>

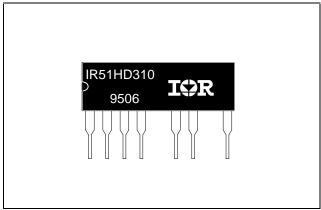
#### **Description**

The IR51HD310 is a high voltage, high speed, selfoscillating half-bridge. Proprietary HVIC and latch immune CMOS technologies, along with HEXFET® power MOSFET technology, enable ruggedized single package construction. The front-end features a programmable oscillator which functions similar to the CMOS 555 timer. The supply to the control circuit has a zener clamp to simplify offline operation. The output features two HEXFETs in a half-bridge configuration with an internally set deadtime designed for minimum cross-conduction in the half-bridge. Propagation delays for the high and low side power MOSFETs are matched to simplify use in 50% duty cycle applications. The device can operate up to 400 volts.

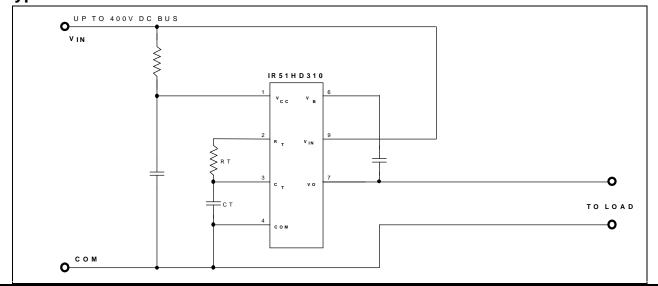
### **Product Summary**

V <sub>IN</sub> (max)	400V
<b>Duty Cycle</b>	50%
Deadtime	1.2µs
R <sub>DS(on)</sub>	<b>3.6</b> Ω
P <sub>D</sub> (T <sub>A</sub> = 25 °C)	2.0W

#### **Package**



## **Typical Connection**





#### **Absolute Maximum Ratings**

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V <sub>IN</sub>	High Voltage Supply	-0.3	400	
$V_{B}$	High Side Floating Supply Absolute Voltage	-0.3	425	
VO	Half-Bridge Output Voltage	-0.3	V+ + 0.3	V
V <sub>RT</sub>	R <sub>T</sub> Voltage	-0.3	V <sub>CC</sub> + 0.3	
V <sub>CT</sub>	C <sub>T</sub> Voltage	-0.3	V <sub>CC</sub> + 0.3	
Icc	Supply Current (Note 1)		25	mA
I <sub>RT</sub>	R <sub>T</sub> Output Current	-5	5	
dv/dt	Peak Diode Recovery dv/dt		4.0	V/ns
P <sub>D</sub>	Package Power Dissipation @ T <sub>A</sub> ≤ +25°C		2.00	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		60	°C/W
TJ	Junction Temperature	-55	150	
Ts	Storage Temperature	-55	150	٥C
$T_L$	Lead Temperature (Soldering, 10 seconds)		300	

#### **Recommended Operating Conditions**

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V <sub>B</sub>	High Side Floating Supply Absolute Voltage	VO + 10	VO + V <sub>CLAMP</sub>	
$V_{IN}$	High Voltage Supply		400	V
VO	Half-Bridge Output Voltage	-5	400	
I <sub>D</sub>	Continuous Drain Current (T <sub>A</sub> = 25°C)		0.70	Α
	$(T_A = 85^{\circ}C)$		0.45	
Icc	Supply Current (Note 1)		5	mA
T <sub>A</sub>	Ambient Temperature	-40	125	°C

Note 1: Because of the IR51HD310's application specificity toward off-line supply systems, this IC contains a zener clamp structure between the chip V<sub>CC</sub> and COM which has a nominal breakdown voltage of 15.6V. Therefore, the IC supply voltage is normally derived by current feeding the V<sub>CC</sub> lead (typically by means of a high value resistor connected between the chip V<sub>CC</sub> and the rectified line voltage and a local decoupling capacitor from V<sub>CC</sub> to COM) and allowing the internal zener clamp circuit to determine the nominal supply voltage. Therefore, this circuit should not be driven by a DC, low impedance power source of greater than V<sub>CLAMP</sub>.



## **Dynamic Electrical Characteristics**

 $V_{BIAS}$  ( $V_{CC}$ ,  $V_{B}$ ) = 12V unless otherwise specified.

	Parameter		$T_A = 25^{\circ}C$			
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
t <sub>rr</sub>	Reverse Recovery Time (MOSFET Body Diode)		240		ns	$I_F = 700 \text{mA}$
Q <sub>rr</sub>	Reverse Recovery Charge (MOSFET Body Diode)		0.85		μC	$di/dt = 100A/\mu s$
DT	Deadtime, LS Turn-Off to HS Turn-On & HS Turn-Off to LS Turn-On		1.2		μs	
D	R <sub>T</sub> Duty Cycle		50		%	$f_{OSC} = 20 \text{ kHz}$

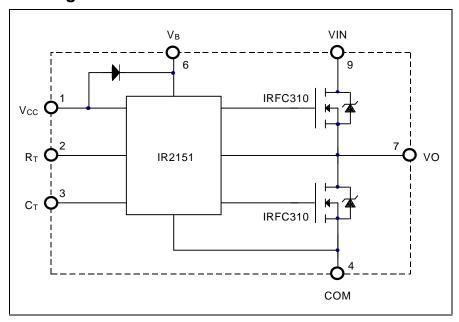
### **Static Electrical Characteristics**

 $V_{BIAS}$  ( $V_{CC}$ ,  $V_{B}$ ) = 12V unless otherwise specified.

	Parameter		$T_A = 25^{\circ}C$			
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
Supply	Characteristics					
V <sub>CCUV+</sub>	V <sub>CC</sub> Supply Undervoltage Positive Going Threshold		8.4		V	
V <sub>CCUV</sub> -	V <sub>CC</sub> Supply Undervoltage Negative Going Threshold		8.0			
Iqcc	Quiescent V <sub>CC</sub> Supply Current		300		μA	
$V_{CLAMP}$	V <sub>CC</sub> Zener Shunt Clamp Voltage		15.6		V	$I_{CC} = 5 \text{ mA}$
Floating	Supply Characteristics					
$I_{QBS}$	Quiescent V <sub>BS</sub> Supply Current		30		μA	
Ios	Offset Supply Leakage Current 50		V			$_{\rm B} = V_{\rm IN} = 400 V$
Oscillate	or I/O Characteristics					
fosc	Oscillator Frequency		20		kHz	$R_T = 35.7 \text{ k}\Omega,$ $C_T = 1 \text{ nF}$
			100			$R_T = 7.04 \text{ k}\Omega,$ $C_T = 1 \text{ nF}$
I <sub>CT</sub>	C <sub>T</sub> Input Current		0.001	1.0	μA	
V <sub>CTUV</sub>	C <sub>T</sub> Undervoltage Lockout 100	)		2.5	V < V	cc < Vccuv-
$V_{RT+}$	R <sub>T</sub> High Level Output Voltage, V <sub>CC</sub> - R <sub>T</sub>		20			$I_{RT} = -100 \mu A$
			200		mV	$I_{RT} = -1 \text{ mA}$
$V_{RT}$	R <sub>T</sub> Low Level Output Voltage		20			$I_{RT} = 100 \mu A$
			200			$I_{RT} = 1 \text{ mA}$
$V_{RTUV}$	R <sub>T</sub> Undervoltage Lockout, V <sub>CC</sub> - R <sub>T</sub>		100			2.5V < V <sub>CC</sub> < V <sub>CCUV+</sub>
V <sub>CT</sub> +	2/3 V <sub>CC</sub> Threshold		8.0		V	
V <sub>CT</sub> -	1/3 V <sub>CC</sub> Threshold		4.0			
Output	Characteristics					
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance		3.6		Ω	$I_D = 700 \text{ mA}$
$V_{SD}$	Diode Forward Voltage 0.8			_	V	Tj = 150 °C



## **Functional Block Diagram**

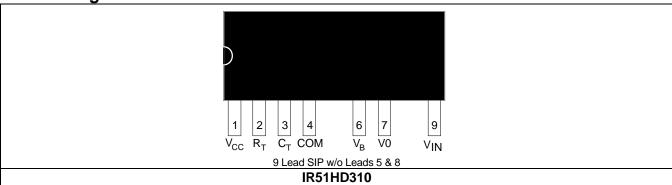


## **Lead Definitions**

Lead				
Symbol	Description			
V <sub>CC</sub>	Logic and internal gate drive supply voltage. An internal zener clamp diode at 15.6 V nominal is included to allow the $V_{CC}$ to be current fed directly from $V_{IN}$ typically by means of a high value resistor.			
R <sub>T</sub>	Oscillator timing resistor input; a resistor is connected from $R_T$ to $C_T$ . $R_T$ is out of phase with the half-bridge output (VO).			
Ст	Oscillator timing capacitor output; a capacitor is connected from C <sub>T</sub> to COM in order to program the oscillator frequency according to the following equation:			
	$f = \frac{1}{1.4 \times (RT + 75\Omega) \times CT}$			
	where 75 $\Omega$ is the effective impedance of the R <sub>T</sub> output stage.			
V <sub>B</sub>	High side gate drive floating supply. For bootstrap operation a high voltage fast recovery diode is needed to feed from $V_{CC}$ to $V_{B}$ .			
$V_{IN}$	High voltage supply.			
VO	Half-bridge output.			
COM	Logic and low side of half-bridge return.			



**Lead Assignments** 



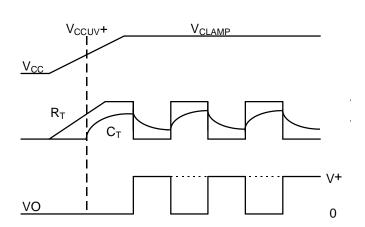


Figure 1. Input/Output Timing Diagram

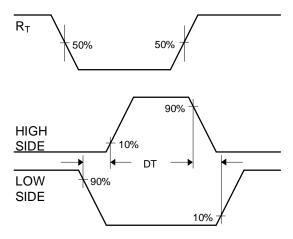
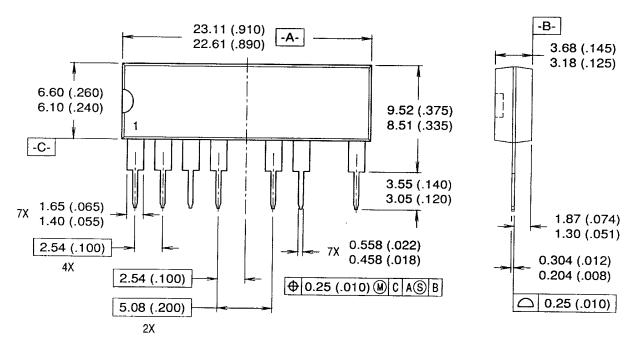


Figure 2. Deadtime Waveform Definitions





#### NOTES:

- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

Package Outline



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